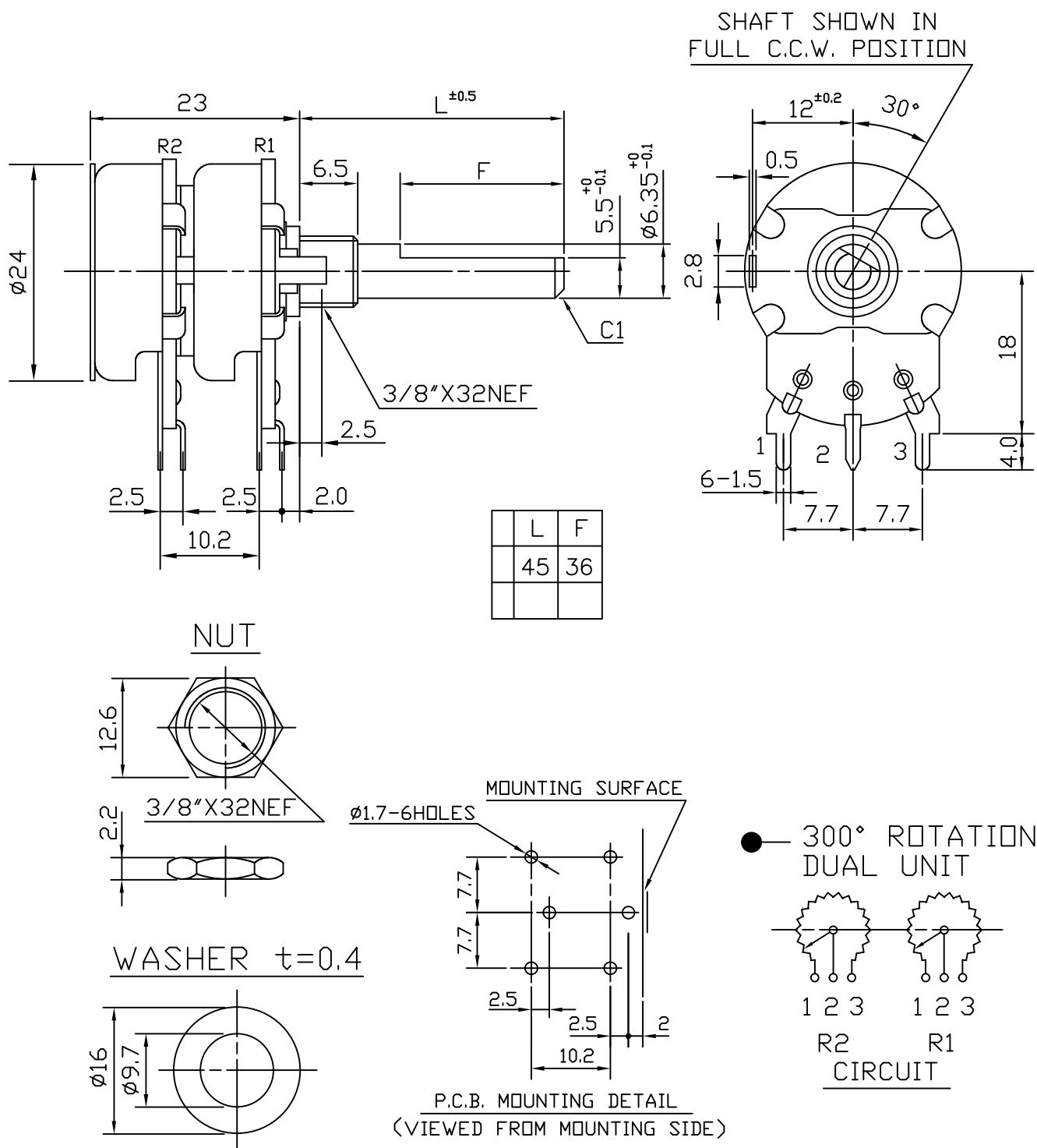




1. MECHANICAL SPECIFICATION

1. OUTSIDE DIMENSION	append fig.	
2. TOTAL ROTATION ANGLE	degree	300 5!
3. TOTAL TRAVEL STROKE	mm	0.5
4. NUT WIRING STRENGTH	twisting moment	less than 9 kgf.cm
5. SCREW TIGHTENING FORCE	torsional moment	less than kgf.cm
6. ROTATION TORQUE	speed 60 deg/sec.	20~200 gf.cm
7. SLIDING FORCE	speed 20mm/sec	gf.cm
8. SHAFT LEVER STRENGTH	pulling pushing	more than kgf.cm
9. SHAFT LEVER WOBBLE	within mm (bending moment	gf.cm)
10. SHAFT LEVER STOP STRENGTH	more than 6 kgf.cm (static load) / 60 sec	
11. TERMINAL STRENGTH	more than 500 gf.cm / 10 1 sec	
	soldering heat 350 5!C/3sec. 200gf.cm/10 1sec	
	resist change within 2%	
12. CLICK POSITION & TORQUE	gf.cm	
13. SWITCH WORKING ANGLE (STROKE)	degree (mm)	
14. SWITCH WORKING TORQUE (FORCE)	gf.cm	
15. SWITCH CIRCUIT		

SHAFT

MATERIAL	ANGLE OF FLAT OR SLOT	DIMENSION			
	\$ at	M	L	F	T
			45		

2. ELECTRICAL SPECIFICATION

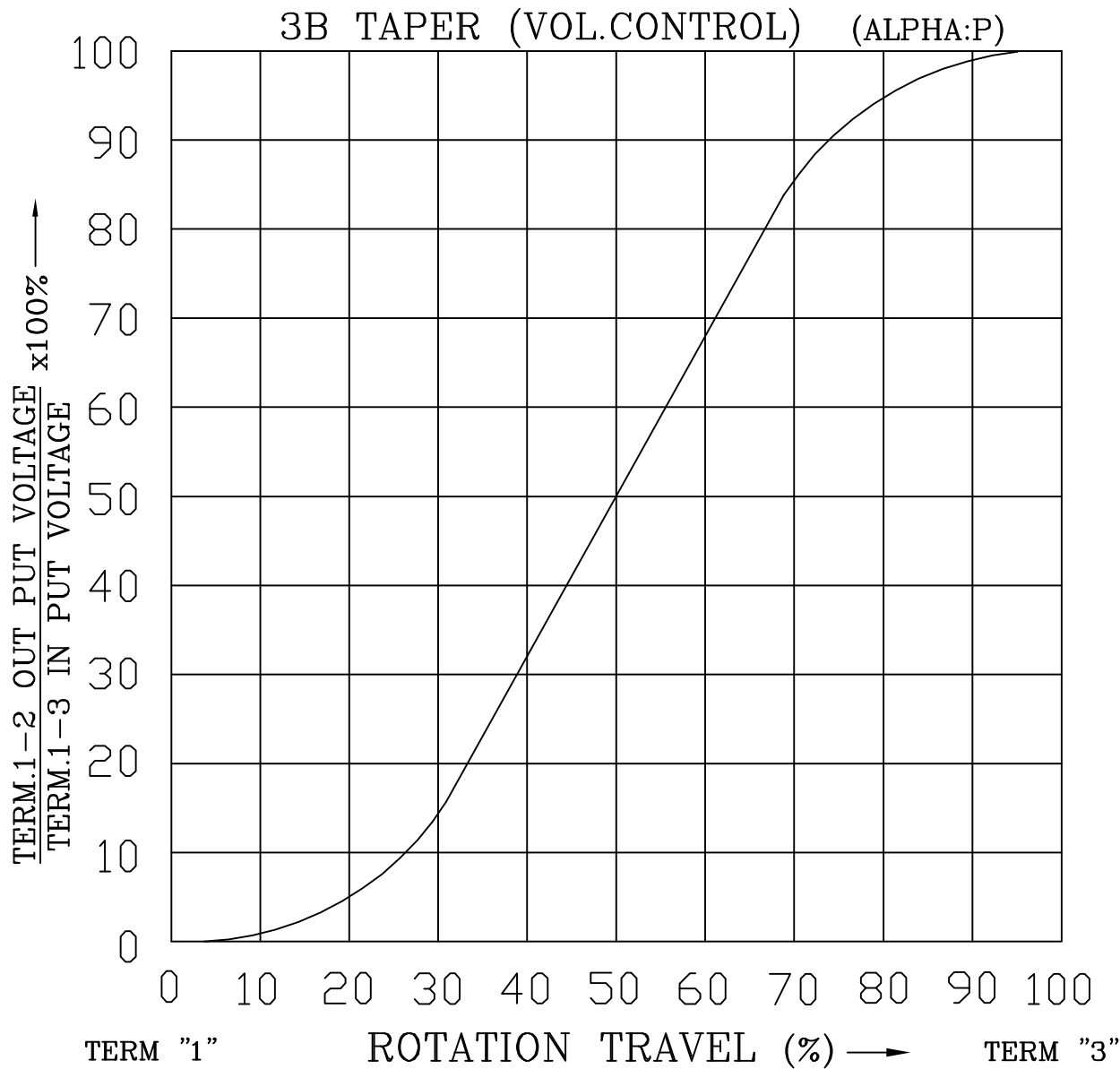
1. OVERALL RESISTANCE & TOLERANCE	terminal 1-3	50 K " 20 %
2. TAP RESISTANCE & TOLERANCE	terminal 1-4	" %
3. RATED WATTAGE	temp 0~50!C	0.5 W
4. MAXIMUM WORKING VOLTAGE		500 V
5. RESISTANCE TAPER MEASURING POINT & TOLERANCE		50 %point 40 ~ 60 %
6. RESIDUAL RESISTANCE	terminal 1/3 side	less than 20/30 "
7. TAP RESIDUAL RESISTANCE	terminal 4 side	less than 100 "
8. SLIDE NOISE	speed 60! / 1 sec	less than 100 mV
9. INSULATION RESISTANCE	more than 100 M" (DC	500 V)
10. WITHSTAND VOLTAGE	AC 500 V	1 minute
11. TRACKING ERROR		-40dB~0dB# 3dB
12. SWITCH CONTACT RESISTANCE	M"	less than m"
13. SWITCH RATING		

3. USABLE TEMPERATURE RANGE: from 10 C to 70 C

4. VR LIFE 15,000 ! TIMES
RESISTANCE CHANGE: within ! %
SLIDE NOISE : less than mV
SW LIFE ! TIMES
CONTACT RESISTANCE: less than m"

REFERENCE NO.	REV

STANDARD RESISTANCE TAPER



Common Specification of Lead-Free Soldering and Storage conditions for Potentiometers

The specification below is based on testing results of 1.6mm thickness single layer printed circuit board.

1. For Manual Soldering

1-1 To be performed within 3 seconds at 350°C or below.

2. For Automated or Semi-Automated Soldering Equipments:

2-1 Flux of 0.82 specific gravity, applied by foam fluxer, shall be used. Foam head shall be limited to the height which is half thickness of printed circuit board to be soldered. No flux should be allowed to run up onto resistive element board of potentiometer and the surface of printed circuit board.

2-2 Regarding preheating, the entire flow duration should not exceed 2 minutes, and soldering surface temperature (undersurface of PCB) shall be settled within 100°C.

2-3 Solder Dipping is to be performed within 4 seconds at 260°C or below.

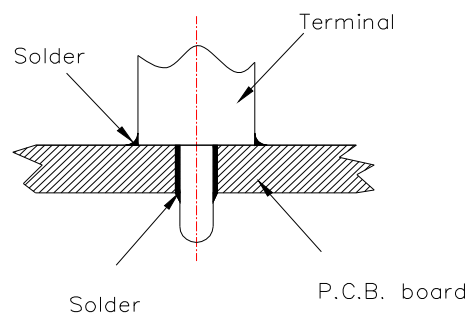
3. For rotary potentiometer with plastic shaft which have centre detent or multiple detents, the shaft should be settled in relevant detent position prior to soldering process.

4. Regardless of soldering facility and method, solder dipping or solder smearing must not be carried out more than 1 time.

Remarks: This specification is not recommended for and applicable in reflow soldering.

Caution for soldering:

Please avoid soldering on upper surface of P.C.B. as shown.



5. The products shall be stored in the original packaging and kept at room temperature and humidity, out of direct sunlight, and away from any and all corrosive gas. The products shall be completely used as soon as possible, but no longer than 6 months from the date of delivery. Once product packaging is opened, the complete quantity of such products shall be promptly used.